

2020 36th Semiconductor Thermal Measurement, Modeling & Management Symposium (SEMI-THERM 2020)

**San Jose, California, USA
16-20 March 2020**



IEEE Catalog Number: CFP20SEM-POD
ISBN: 978-1-7281-9588-9

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IEEE Catalog Number:	CFP20SEM-POD
ISBN (Print-On-Demand):	978-1-7281-9588-9
ISBN (Online):	978-0-578-43862-7

Additional Copies of This Publication Are Available From:

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SUBMIT A PAPER FOR SEMI-THERM 37!

As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 37** will begin accepting abstracts during the summer (deadline is September 15, 2020). We welcome your submissions! Visit us at www.semi-therm.org.

SEMI-THERM 37 is March 16-20, 2021 – be there!

* -- This presentation has no formal paper.